PRODUCTION SOCKETS

IC SOCKETS
ZIP SOCKETS
SIS SOCKETS

INTRODUCTION:
Adam Tech Production Sockets perform a valuable function at a very low cost. They eliminate the need to solder expensive components directly to the PC board. Added advantages include the ability to replace components during repair, reprogramming, and expansion. Our sockets are a low profile design using high pressure dual wipe contacts that conform to EIA RS415 and MIL-S-83734 standards. These high pressure wiping contacts ensure constant continuity and low resistance. The insulators feature wide entry areas for easy lead insertion, an anti-overstress contact stop and a closed bottom to eliminate solder wicking, bridging and contact area contamination.

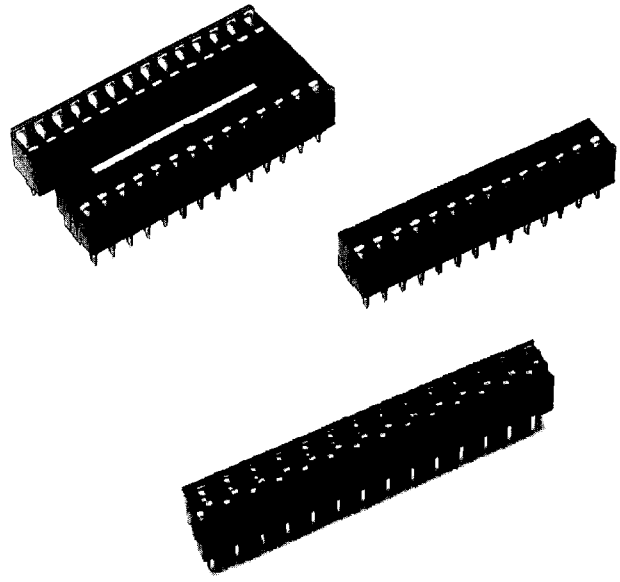
FEATURES:
- ❑ Low profile heights
- ❑ Dual wipe high pressure contacts
- ❑ Wide entry area for easy lead insertion
- ❑ Auto-insertion compatible
- ❑ Visual and mechanical polarization on IC Sockets
- ❑ Anti-overstress contact design

MATING OPTIONS:
Mates with all integrated circuits or components in DIP, SIP and ZIP packages.

SPECIFICATIONS:
Material:
Insulator: Polybutylene Terephthalate (PBT), glass reinforced, thermoplastic, rated UL 94V-0
Contacts: Phosphor Bronze
Plating:
100 µin bright tin-lead plate to MIL-T-10727, Type 1 over 50 µin copper underplate to MIL-C-14550
Electrical:
Operation voltage: 250 VAC max
Current rating: 1 Amp max
Contact resistance: 20 mΩ max
Insulation resistance: 5000 MΩ min @ 1000 VDC between adjacent contacts (75° F and 50% R.H.)
Dielectric withstanding voltage: 1000 VAC min rms (sea level)
Capacitance: .5 pF max between adjacent centers
Mechanical:
Insertion force: 325 gms max per contact
Withdrawal force: 24 gms min per contact
Environmental:
Operating temperature: -65°C to +125°C

PACKAGING:
Anti-static plastic tubes

APPROVALS AND CERTIFICATIONS:
Recognized under the component program of Underwriters Laboratories, Inc. No. E167232
Certified by Canadian Standards Association No. LR 75112



ORDERING INFORMATION

ICS	6	28	T

SERIES INDICATOR
ICS = IC Socket

ROW SPACING
3 = .300" row spacing
Positions: 06, 08, 14, 16, 18, 20, 24, 28
6 = .600" row spacing
Positions: 20, 24, 28, 32, 40, 48

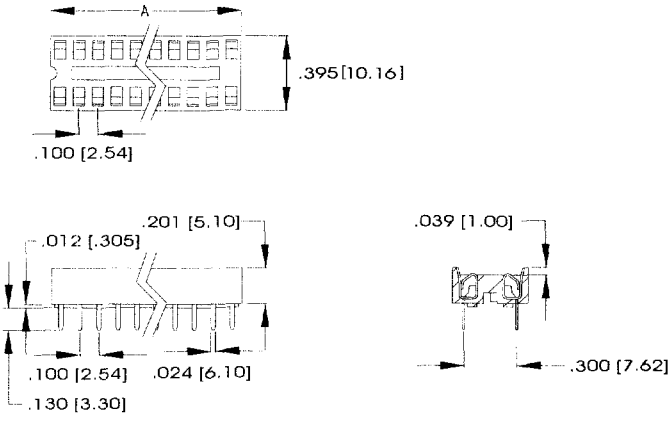
POSITIONS
06 Thru 48

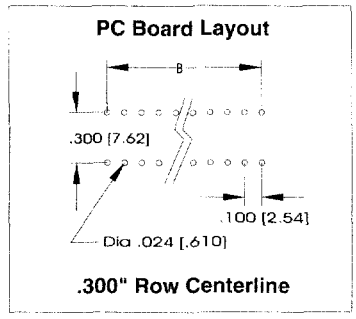
PLATING
T = Tin plated

OPTIONS:
Add as suffix to basic part number
OF = Open Frame without center bar

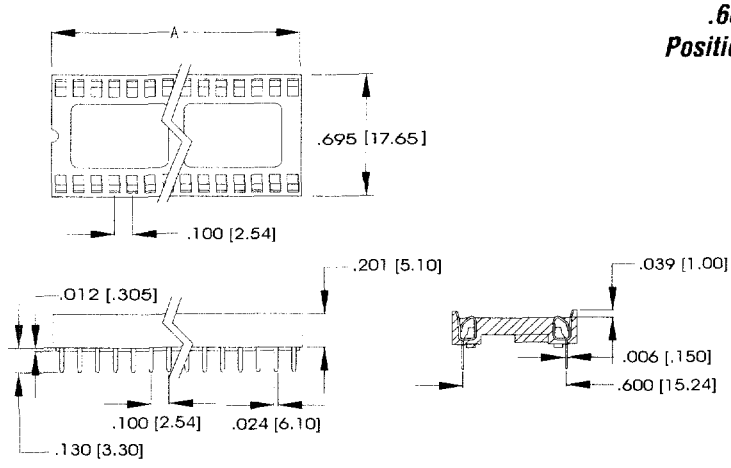
PRODUCTION SOCKETS
.100" [2.54] CENTERLINE
ICS SERIES

.300" Row Centerline Socket
Positions: 6, 8, 14, 16, 18, 20, 24, 28

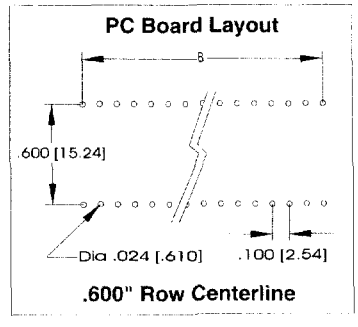




.600" Row Centerline Socket
Positions: 20, 24, 28, 32, 40, 48

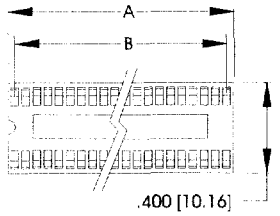


A = .100 x No. of Positions Per Row



PRODUCTION SOCKETS
.070" [1.78] SHRINK DIP SOCKET
ICS SERIES

.300" ROW CENTERLINE



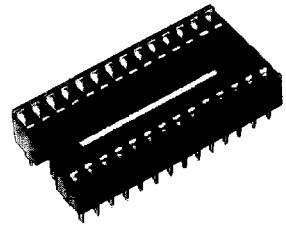
ORDERING INFORMATION

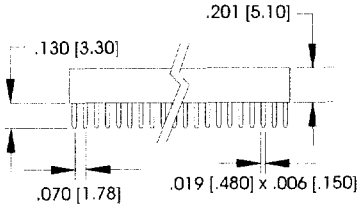
ISD | 28 | T

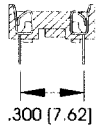
SERIES INDICATOR
ISD = Shrink Dip IC Socket

NO. OF POSITIONS
24, 28, 30

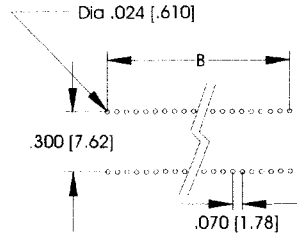
PLATING
T = Tin Plating







PC Board Layout



A = .070 [1.78] x No. of Positions Per Row
B = .070 [1.78] x No. of Spaces

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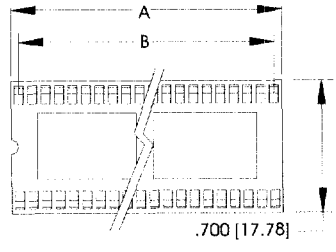
.600" ROW CENTERLINE



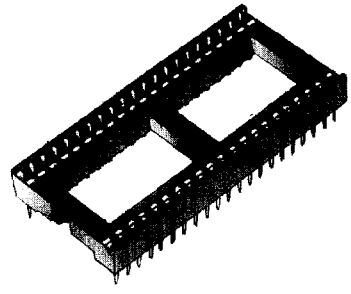
ORDERING INFORMATION

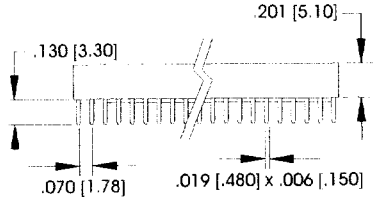
ISD | 42 | T

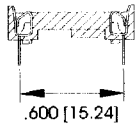
SERIES INDICATOR
ISD = Shrink Dip IC Socket

NO. OF POSITIONS
40P, 42P (.600" Row Spacing),
64P (.750" Row Spacing)

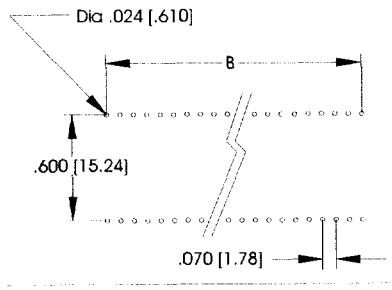
PLATING
T = Tin Plating







PC Board Layout



A = .070 [1.78] x No. of Positions Per Row
B = .070 [1.78] x No. of Spaces

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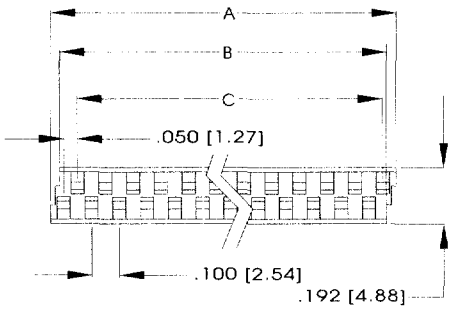
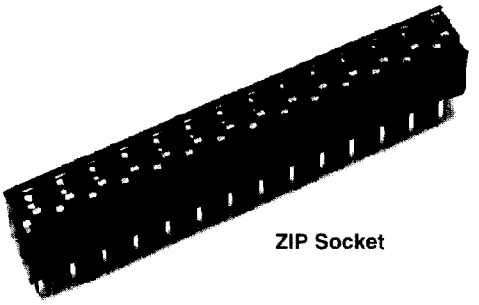
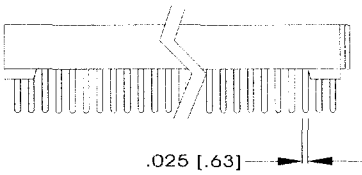
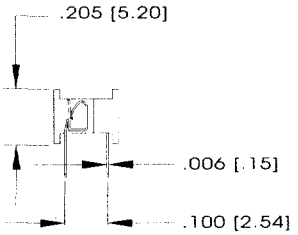
PRODUCTION SOCKETS
ZIP / SIS PACKAGE




ZIP Socket





A = .050" [1.27] x No. of Positions + .016" [.406]
B = .050" [1.27] x No. of Positions
C = .050" [1.27] x No. of Spaces

Specifications on Page 118

ORDERING INFORMATION

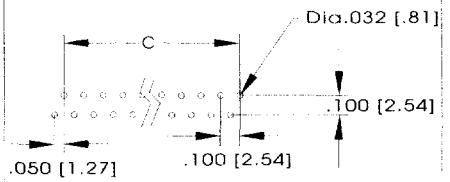
ZIP | 28 | T

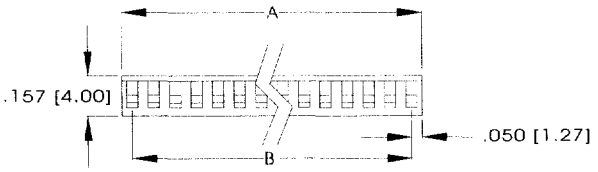
SERIES INDICATOR
ZIP = Staggered Socket

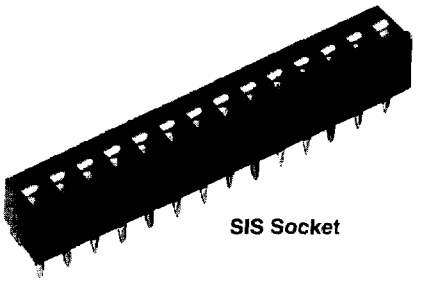
POSITIONS
16, 18, 20, 24, 28, 40

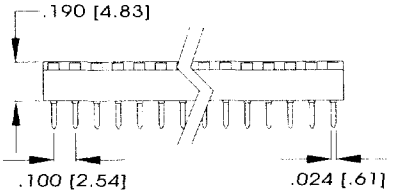
PLATING
T = Tin Plated

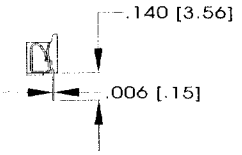
PC Board Layout






SIS Socket





A = .100" [2.54] x No. of Positions
B = .100" [2.54] x No. of Spaces

Specifications on Page 118

ORDERING INFORMATION

SIS | 14 | T

SERIES INDICATOR
SIS = Single In Line Socket

POSITIONS
02 thru 20

PLATING
T = Tin Plated

PC Board Layout